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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	32
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-32-32-7vni

The ispMACH 4A family offers 20 density-I/O combinations in Thin Quad Flat Pack (TQFP), Plastic Quad Flat Pack (PQFP), Plastic Leaded Chip Carrier (PLCC), Ball Grid Array (BGA), fine-pitch BGA (fpBGA), and chip-array BGA (caBGA) packages ranging from 44 to 388 pins (Table 3). It also offers I/O safety features for mixed-voltage designs so that the 3.3-V devices can accept 5-V inputs, and 5-V devices do not overdrive 3.3-V inputs. Additional features include Bus-Friendly inputs and I/Os, a programmable power-down mode for extra power savings and individual output slew rate control for the highest speed transition or for the lowest noise transition.

Table 3. ispMACH 4A Package and I/O Options (Number of I/Os and dedicated inputs in Table)

3.3 V Devices								
Package	**M4A3-32**	**M4A3-64**	**M4A3-96**	**M4A3-128**	**M4A3-192**	**M4A3-256**	**M4A3-384**	**M4A3-512**
44-pin PLCC	32+2	32+2						
44-pin TQFP	32+2	32+2						
48-pin TQFP	32+2	32+2						
100-pin TQFP		64+6	48+8	64+6				
100-pin PQFP				64+6				
100-ball caBGA				64+6				
144-pin TQFP					96+16			
144-ball fpBGA					96+16			
208-pin PQFP						128+14, 160	160	160
256-ball fpBGA						128+14, 192	192	192
256-ball BGA						128+14	192	
388-ball fpBGA								256

5 V Devices						
Package	**M4A5-32**	**M4A5-64**	**M4A5-96**	**M4A5-128**	**M4A5-192**	**M4A5-256**
44-pin PLCC	32+2	32+2				
44-pin TQFP	32+2	32+2				
48-pin TQFP	32+2	32+2				
100-pin TQFP			48+8	64+6		
100-pin PQFP				64+6		
144-pin TQFP					96+16	
208-pin PQFP						128+14

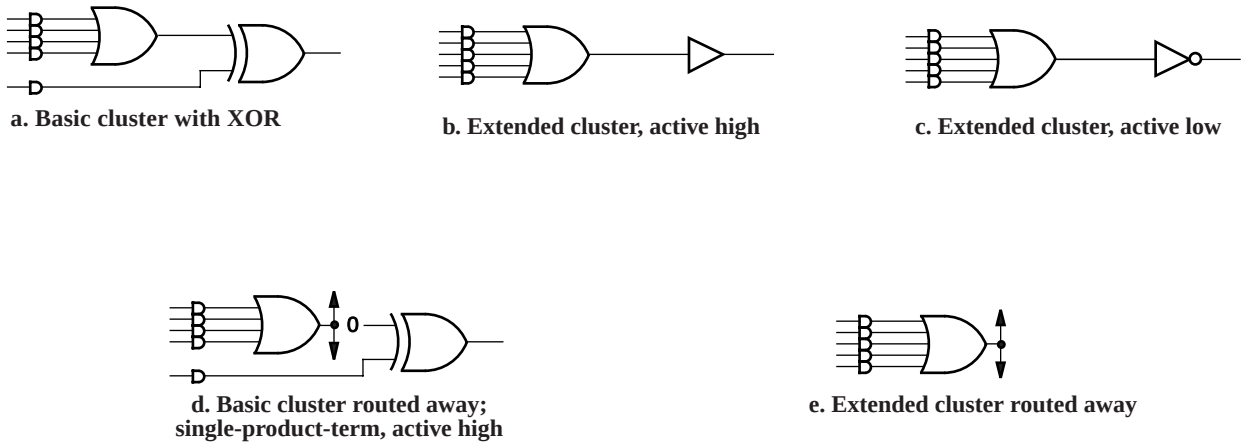


Figure 3. Logic Allocator Configurations: Synchronous Mode

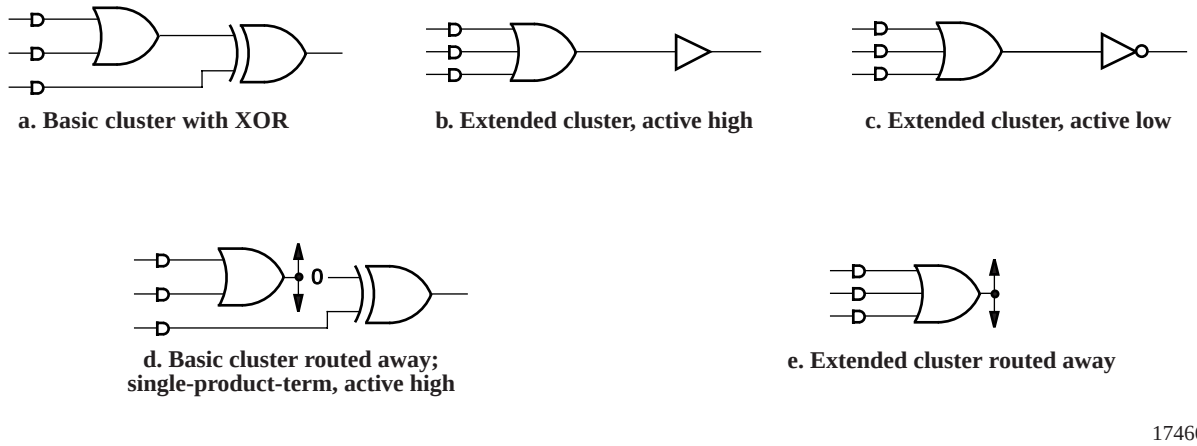


Figure 4. Logic Allocator Configurations: Asynchronous Mode

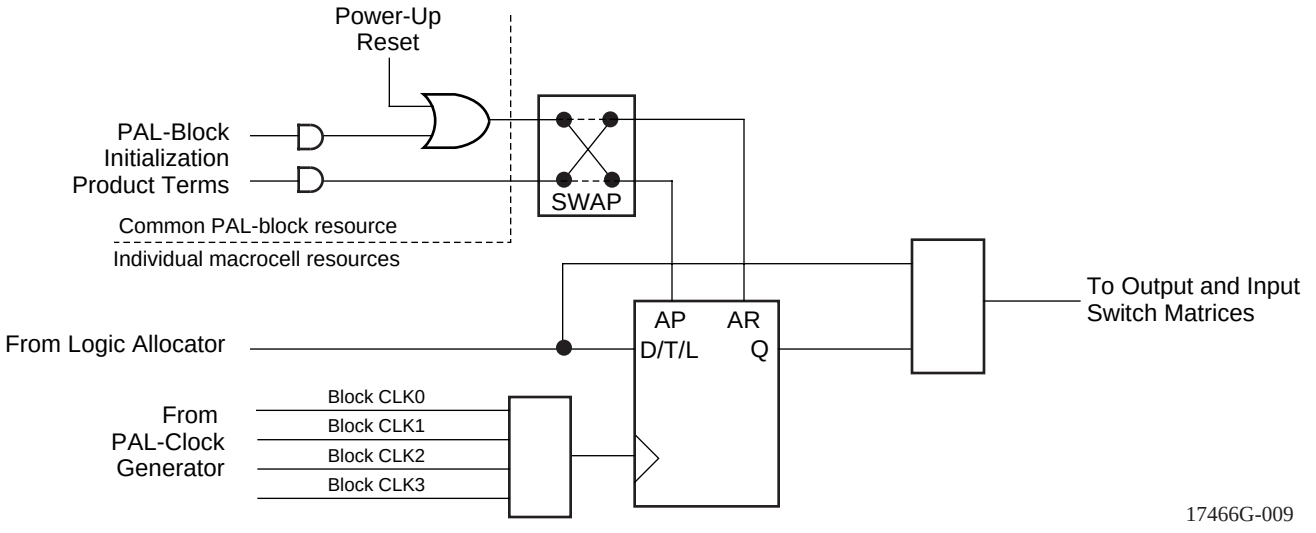
Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

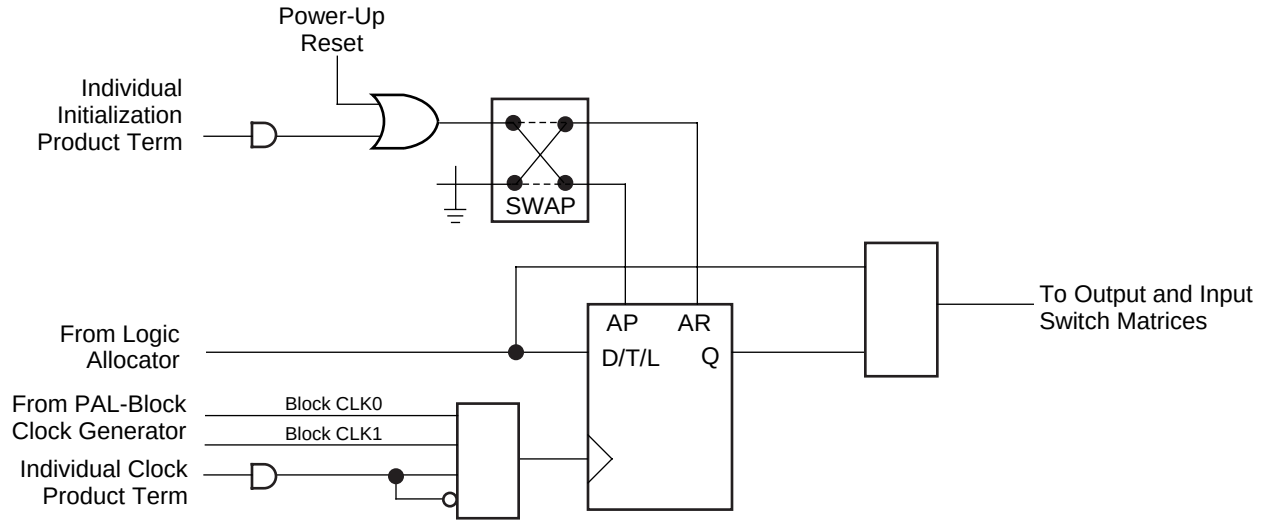
Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode



b. Asynchronous mode

Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE [1]	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	$\overline{Q}$
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

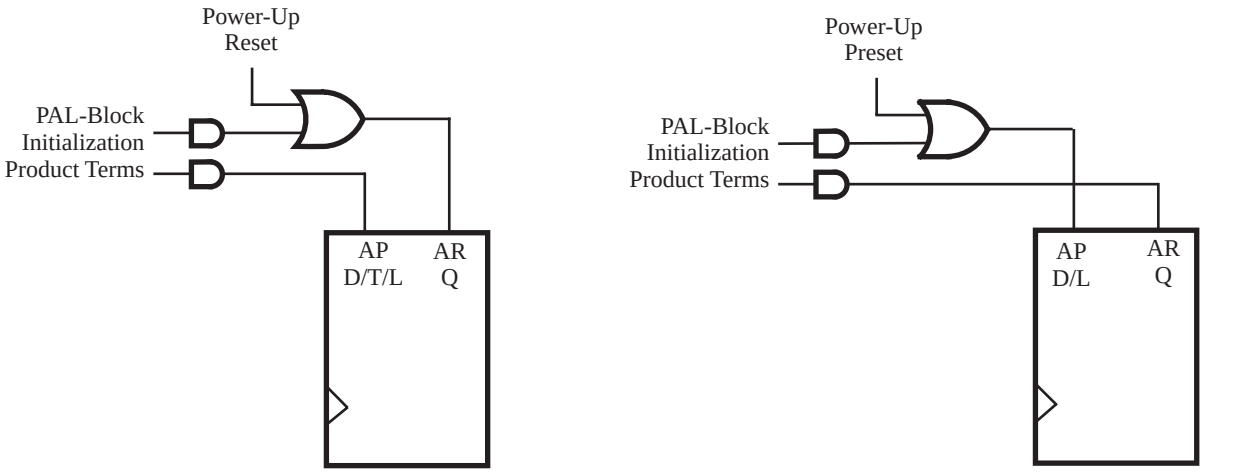
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset **b. Power-up preset**

17466G-012 17466G-013

Figure 7. Synchronous Mode Initialization Configurations

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.

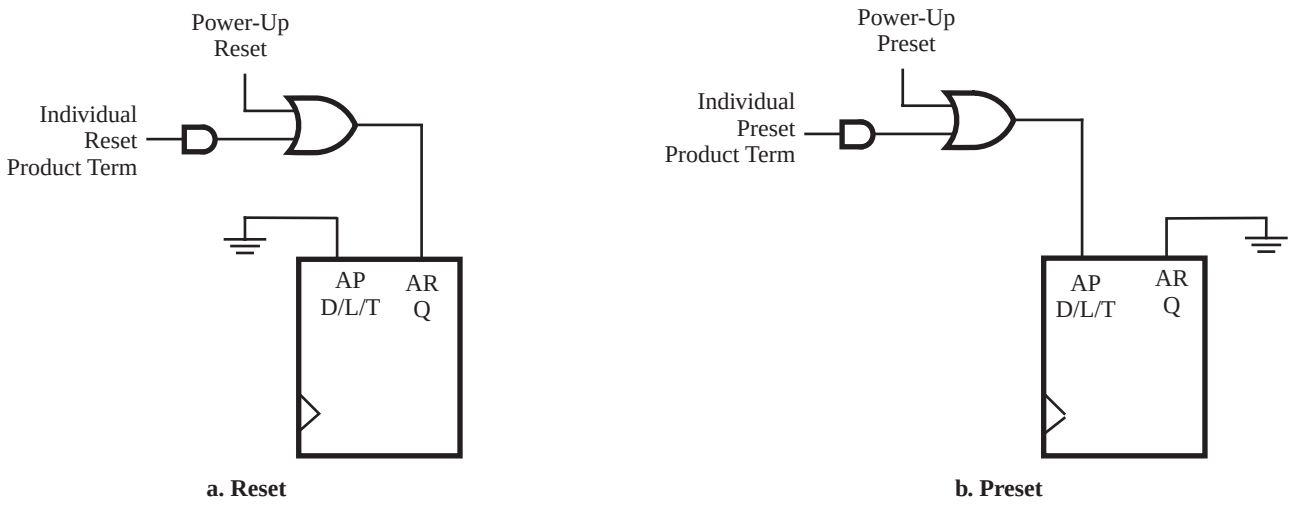


Figure 8. Asynchronous Mode Initialization Configurations

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

AR	AP	CLK/LE[1]	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:

1. Transparent latch is unaffected by AR, AP

Output Switch Matrix

The output switch matrix allows macrocells to be connected to any of several I/O cells within a PAL block. This provides high flexibility in determining pinout and allows design changes to occur without effecting pinout.

In ispMACH 4A devices with 2:1 Macrocell-I/O cell ratio, each PAL block has twice as many macrocells as I/O cells. The ispMACH 4A output switch matrix allows for half of the macrocells to drive I/O cells within a PAL block, in combinations according to Figure 9. Each I/O cell can choose from eight macrocells; each macrocell has a choice of four I/O cells. The ispMACH 4A devices with 1:1 Macrocell-I/O cell ratio allow each macrocell to drive one of eight I/O cells (Figure 9).

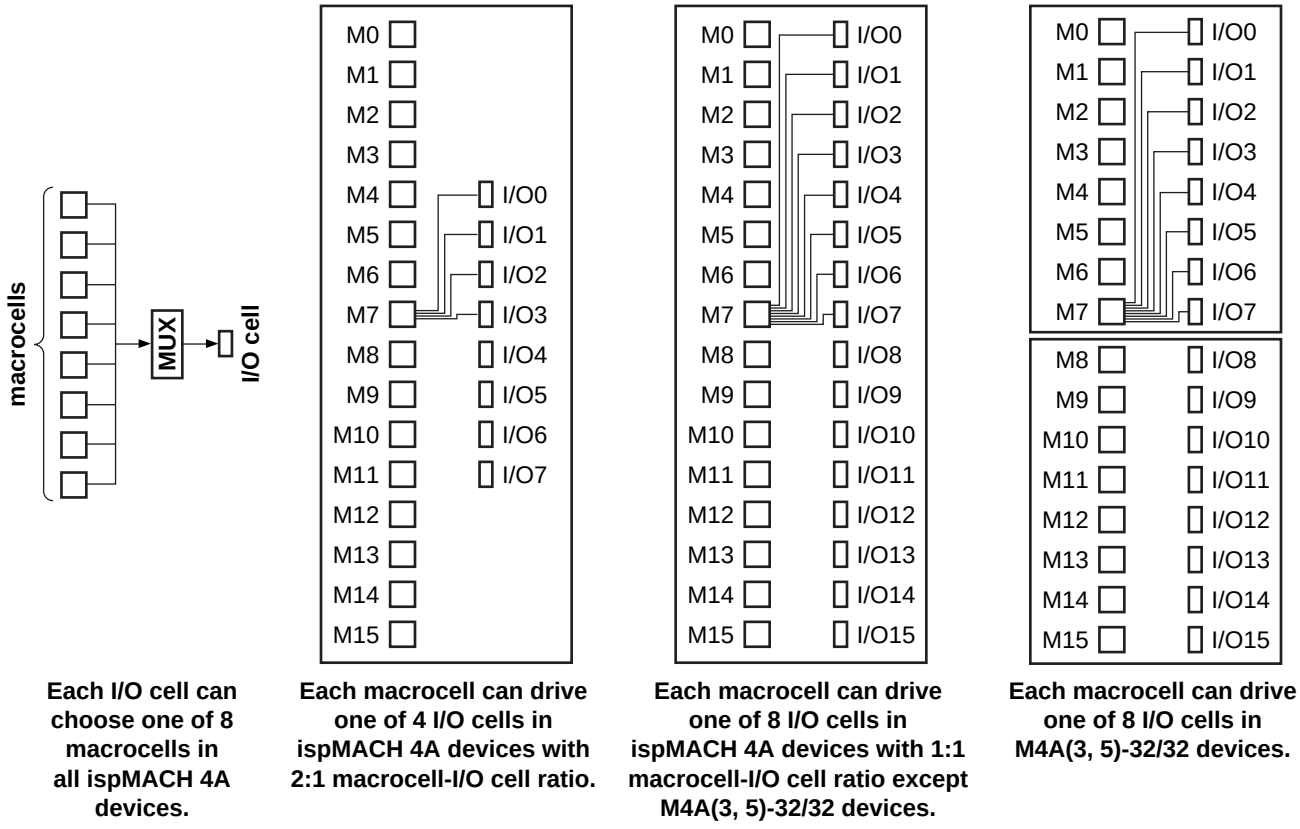


Figure 9. ispMACH 4A Output Switch Matrix

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M0, M1	I/O0, I/O5, I/O6, I/O7
M2, M3	I/O0, I/O1, I/O6, I/O7
M4, M5	I/O0, I/O1, I/O2, I/O7
M6, M7	I/O0, I/O1, I/O2, I/O3
M8, M9	I/O1, I/O2, I/O3, I/O4
M10, M11	I/O2, I/O3, I/O4, I/O5

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.

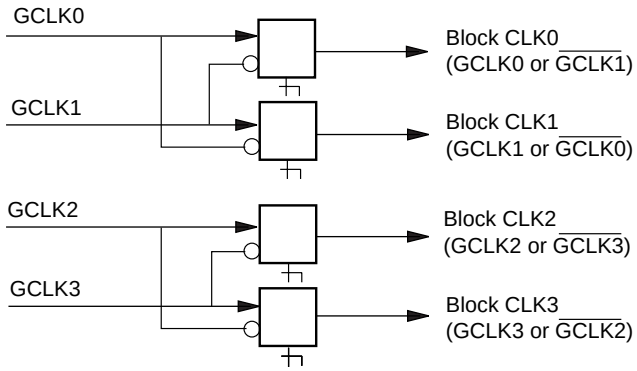


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Figure 14. PAL Block Clock Generator [1]

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations[1]

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
$\overline{\text{GCLK1}}$	GCLK1	X	X
GCLK0	$\overline{\text{GCLK0}}$	X	X
$\overline{\text{GCLK1}}$	$\overline{\text{GCLK0}}$	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)

Note:

1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

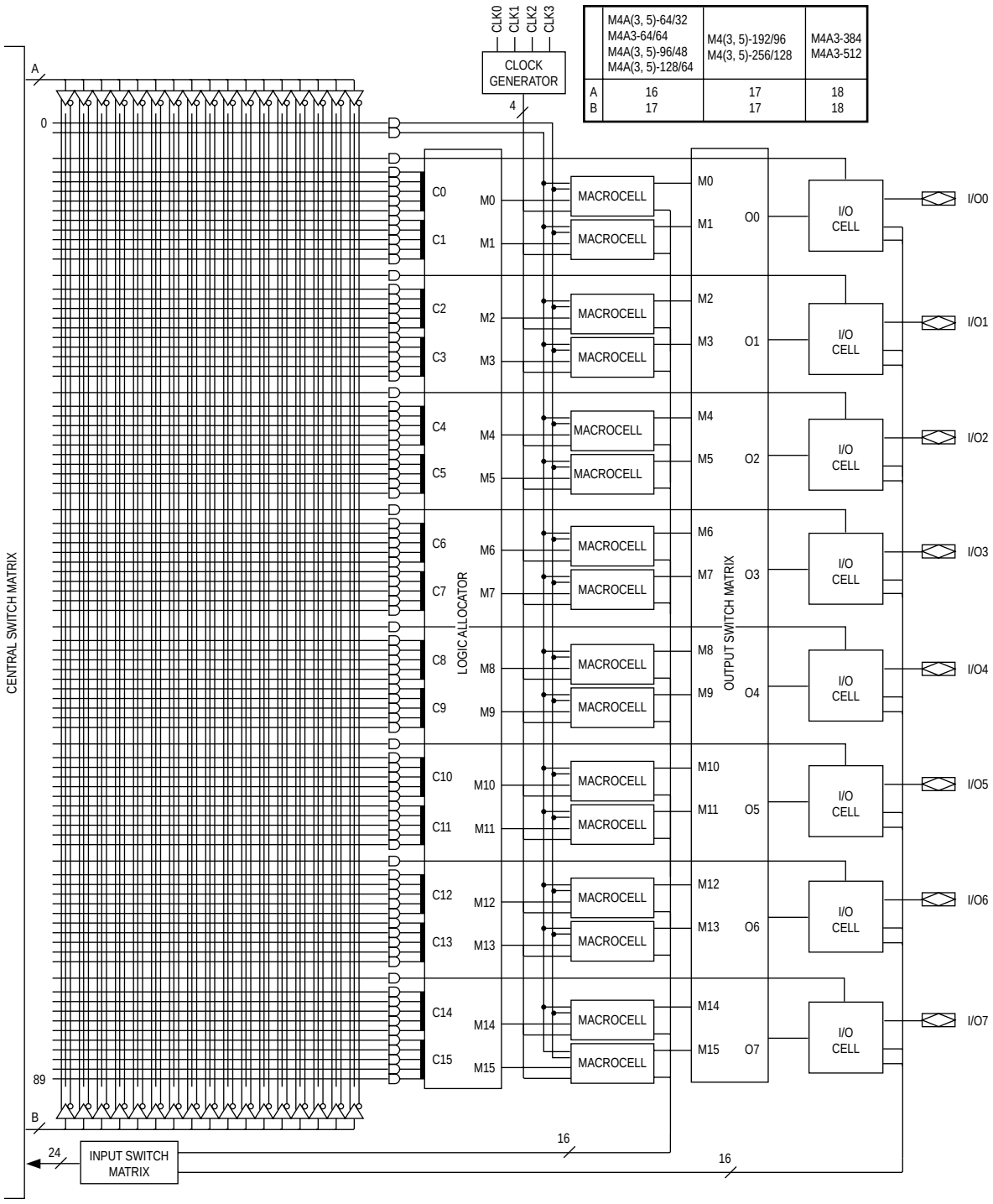
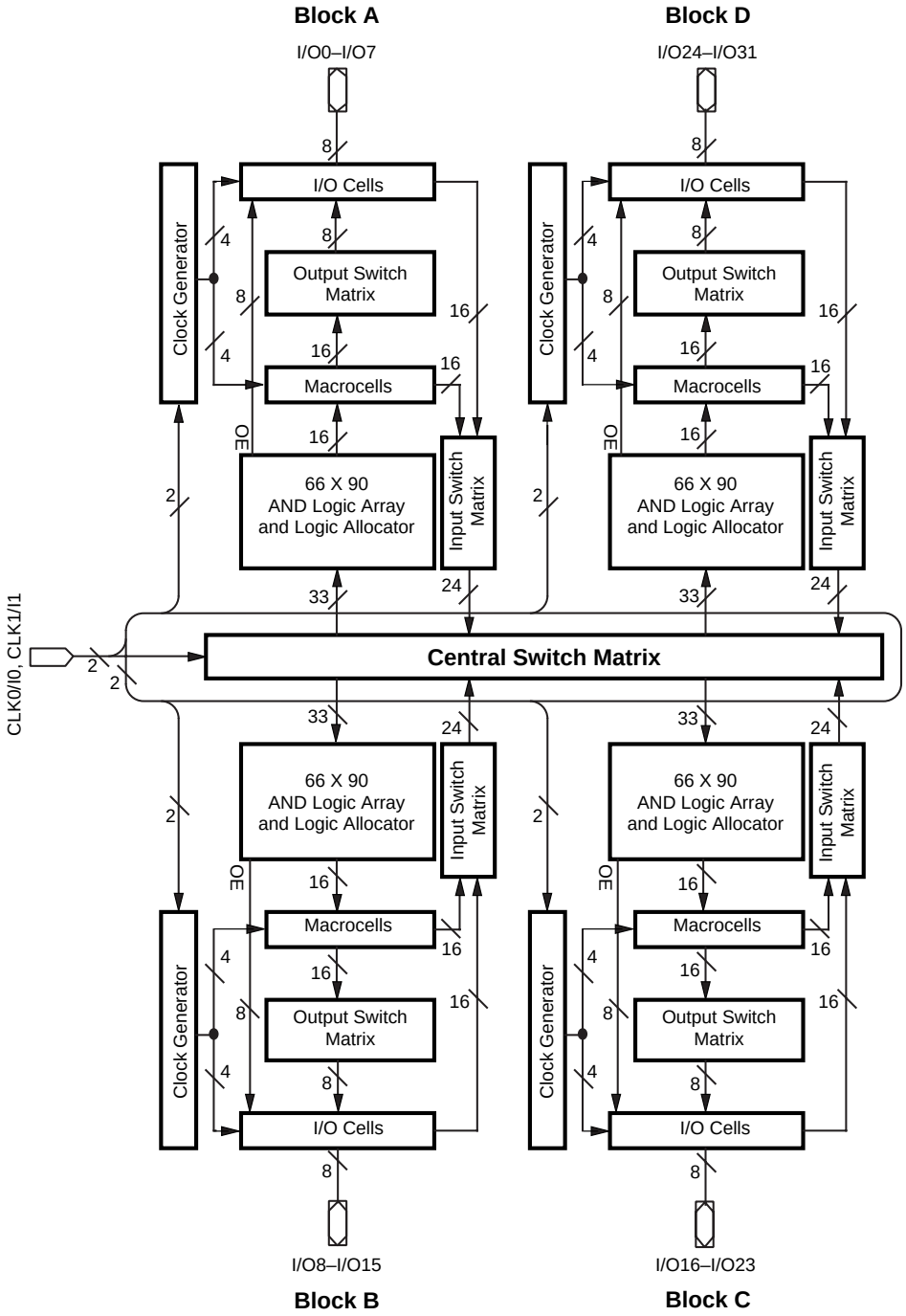


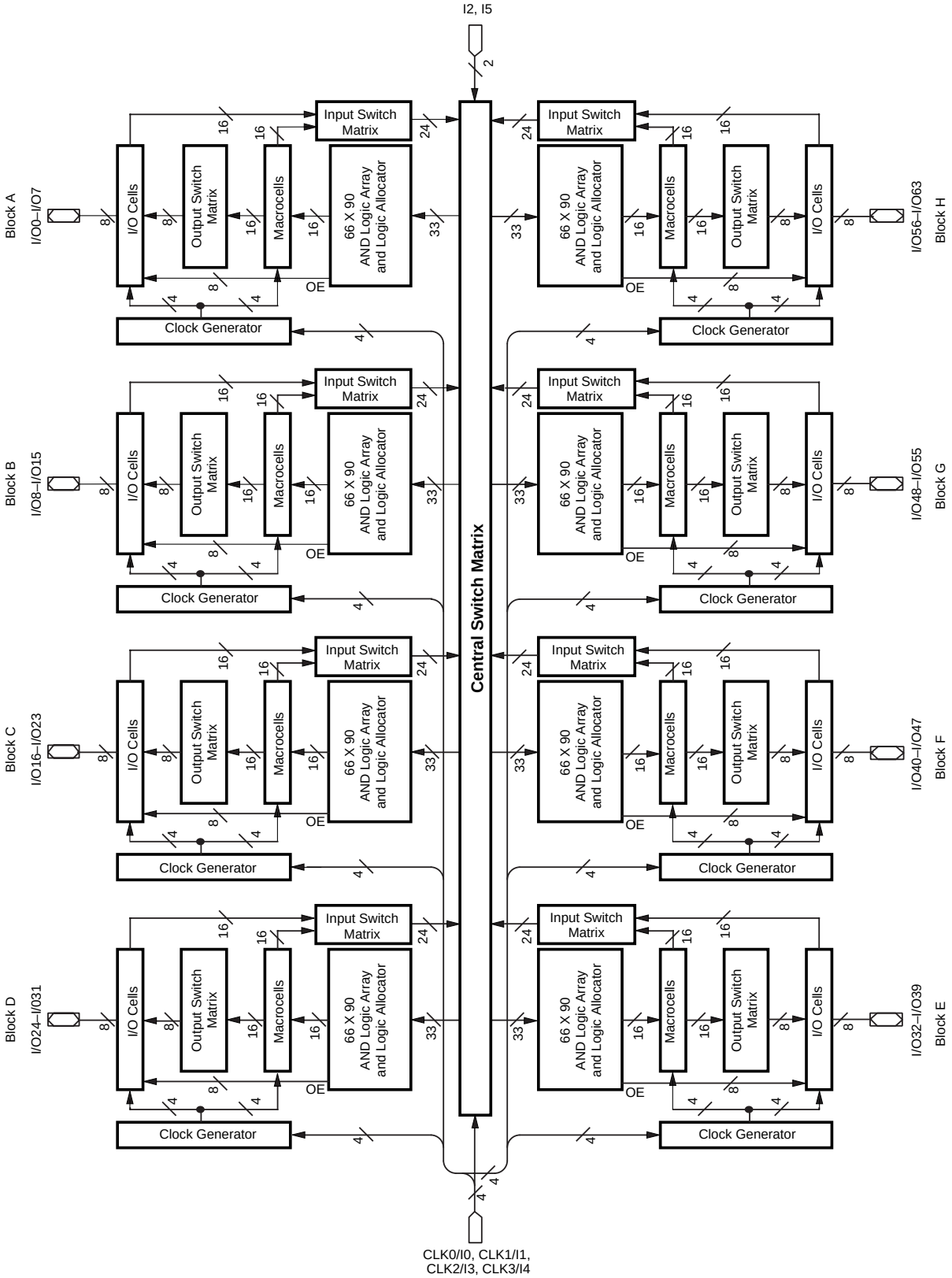
Figure 16. PAL Block for ispMACH 4A with 2:1 Macrocell - I/O Cell Ratio

BLOCK DIAGRAM – M4A(3,5)-64/32



17466H-020

BLOCK DIAGRAM – M4A(3,5)-128/64



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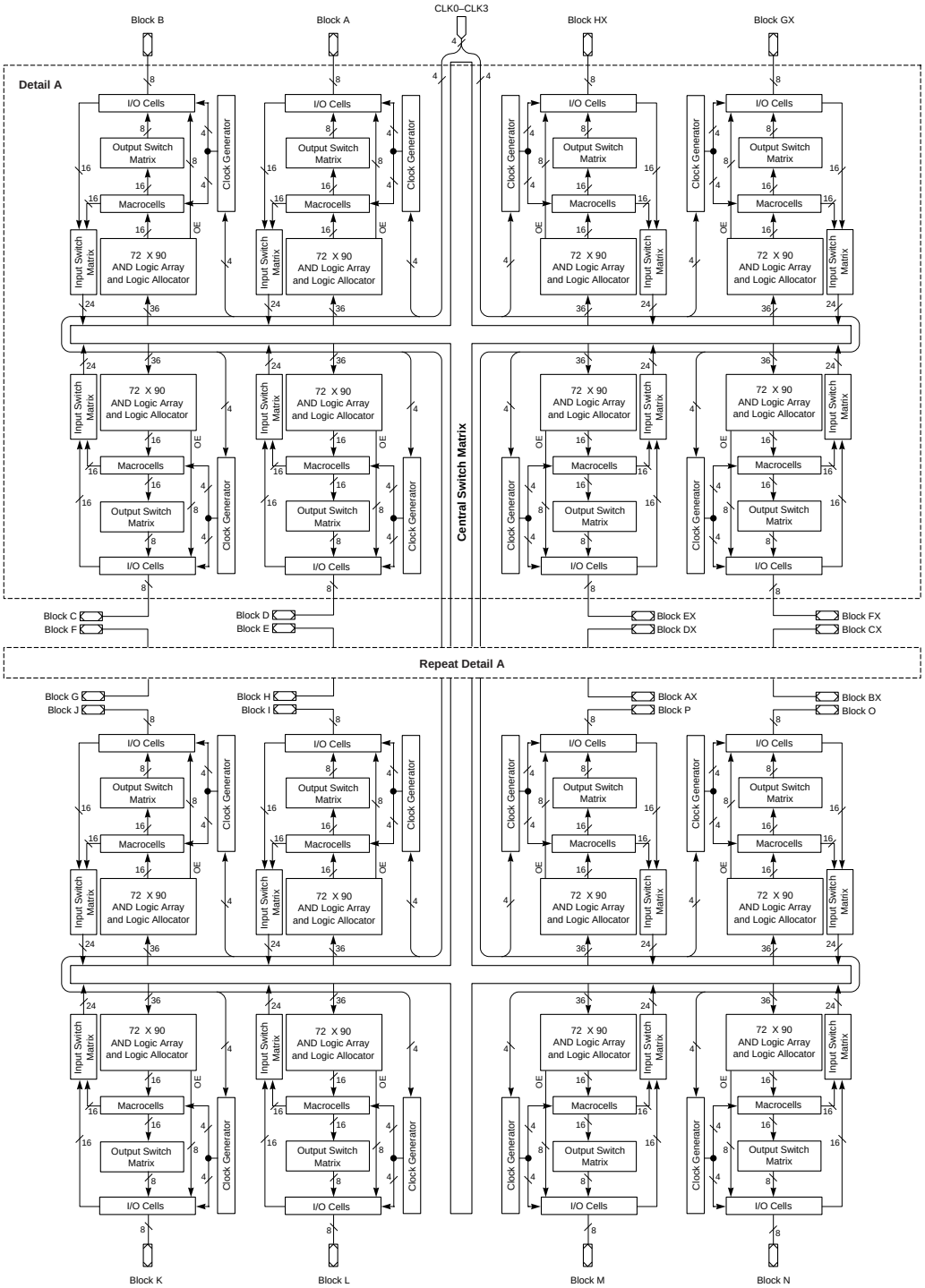
BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



17466G-067

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature . . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . . -55°C to +100°C

Device Junction Temperature. . . . . +130°C

Supply Voltage
with Respect to Ground . . . . . -0.5 V to +4.5 V

DC Input Voltage . . . . . -0.5 V to 6.0 V

Static Discharge Voltage . . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . . 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . -40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	I_{OH} = –100 µA	V_{CC} – 0.2			V
			I_{OH} = –3.2 mA	2.4			V
V_{OL}	Output LOW Voltage	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} (Note 1)	I_{OL} = 100 µA			0.2	V
			I_{OL} = 24 mA			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		–0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 3.6 V, V_{CC} = Max (Note 2)				5	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 2)				–5	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 3.6 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 2)				5	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 2)				–5	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 3)		–15		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
3. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.*

Notes:

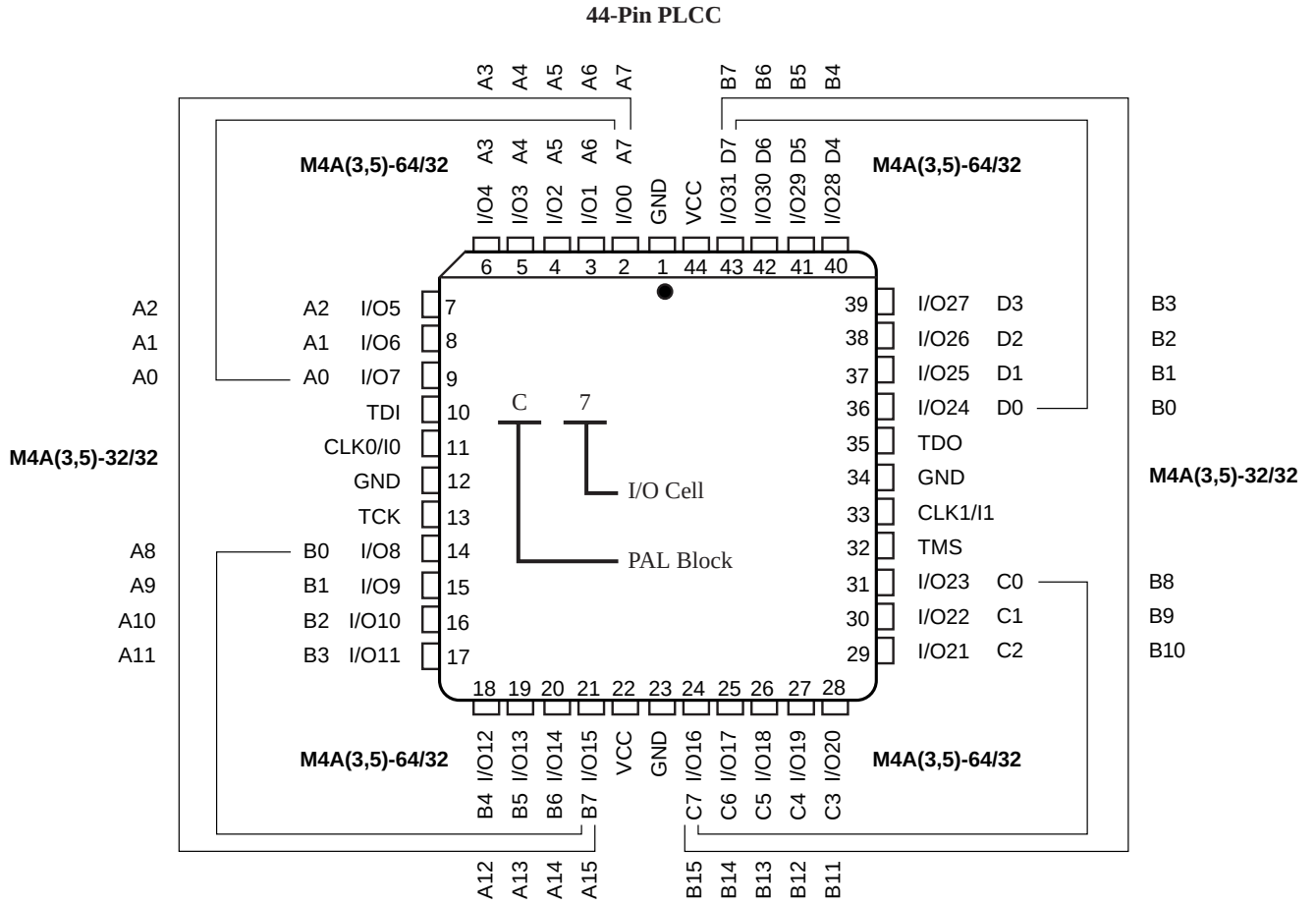
1. *See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.*
2. *This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.*

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES[1]

		-5		-55		-6		-65		-7		-10		-12		-14		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
Input Register Delays with ZHT Option:																		
t_{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t_{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t_{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t_{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t_{PDILZi}	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t_{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t_{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t_{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t_{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t_{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t_{SRi}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t_{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t_{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t_{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t_{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t_{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t_{WLA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t_{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t_{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t_{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t_{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t_{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t_{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

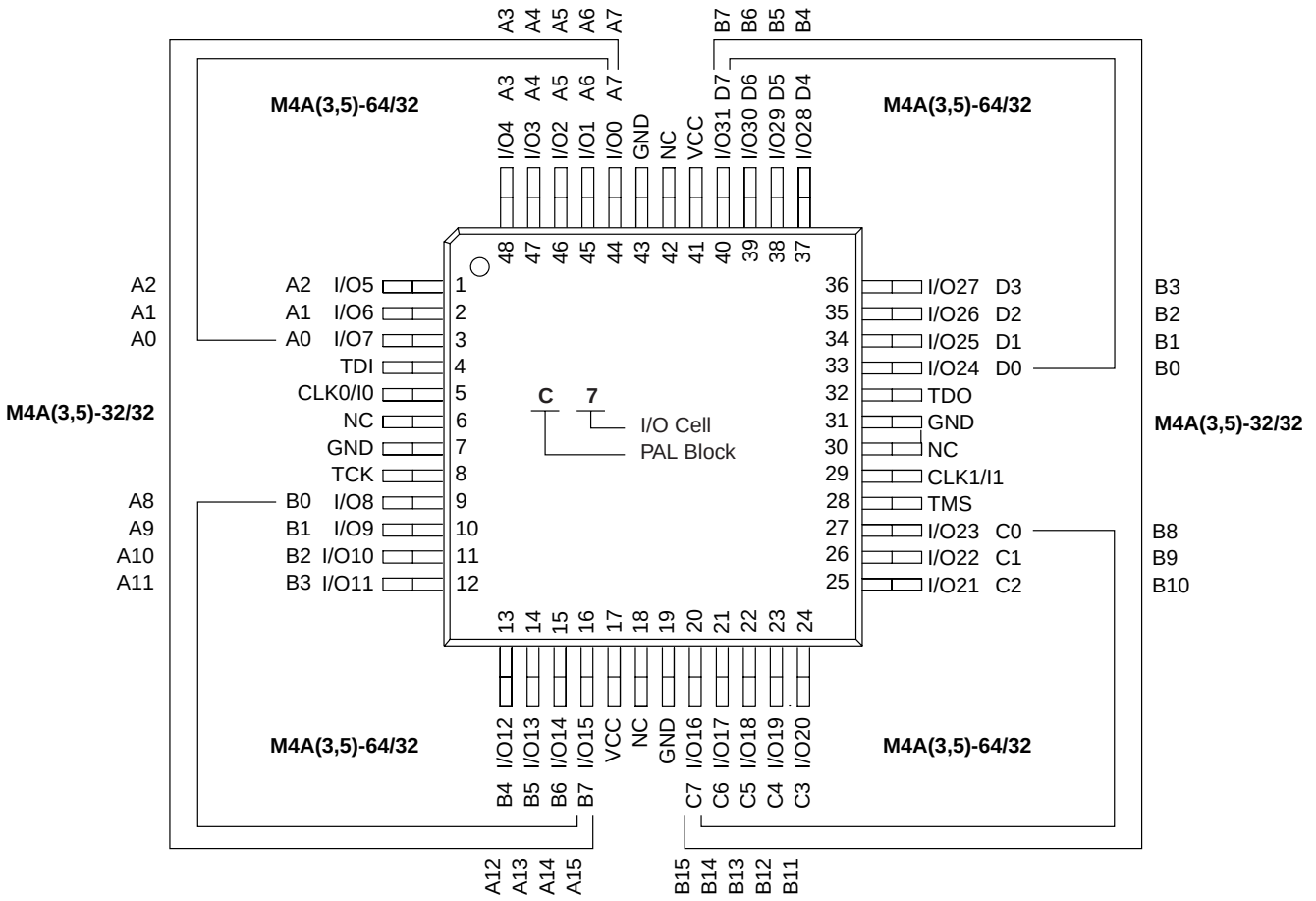
TMS = Test Mode Select

TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

TCK = Test Clock

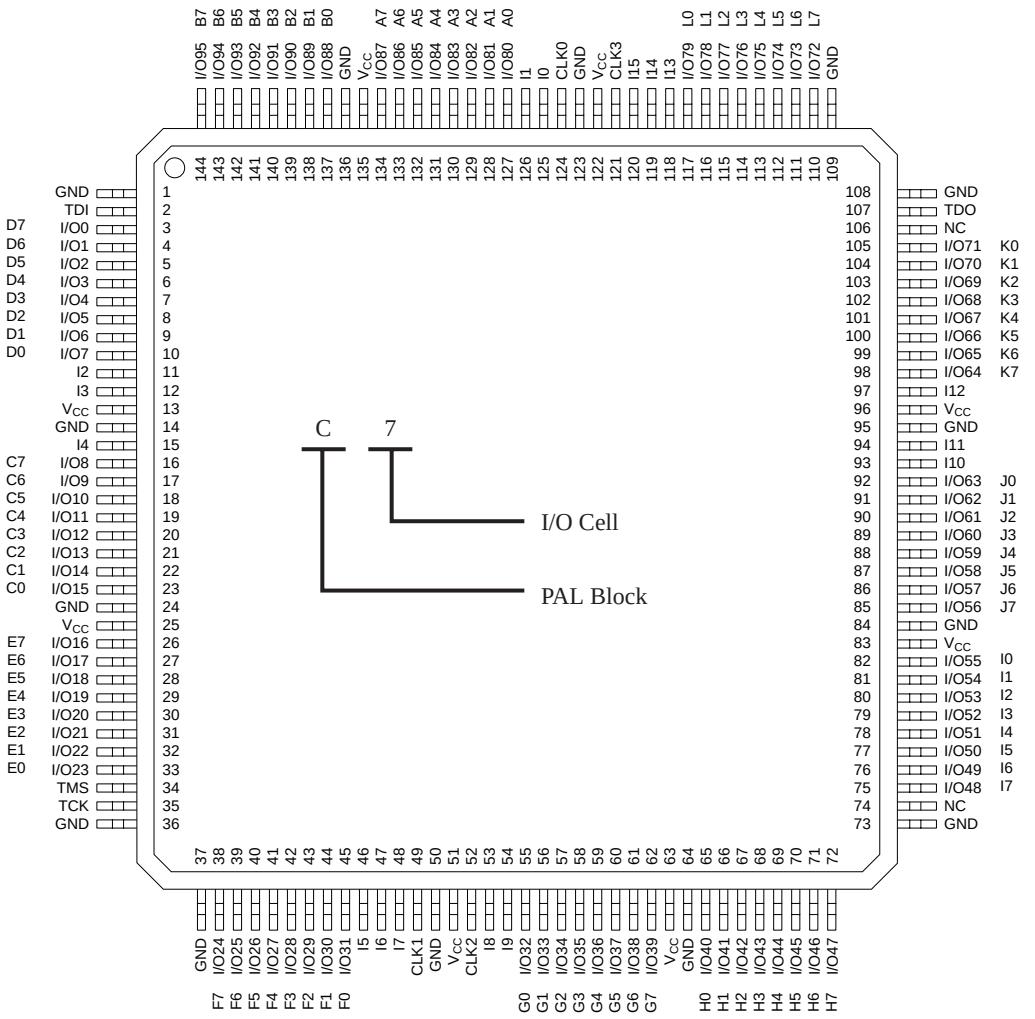
TMS = Test Mode Select

TDO = Test Data Out

144-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-192/96)

Top View

144-Pin TQFP



17466G-033

PIN DESIGNATIONS

CLK = Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

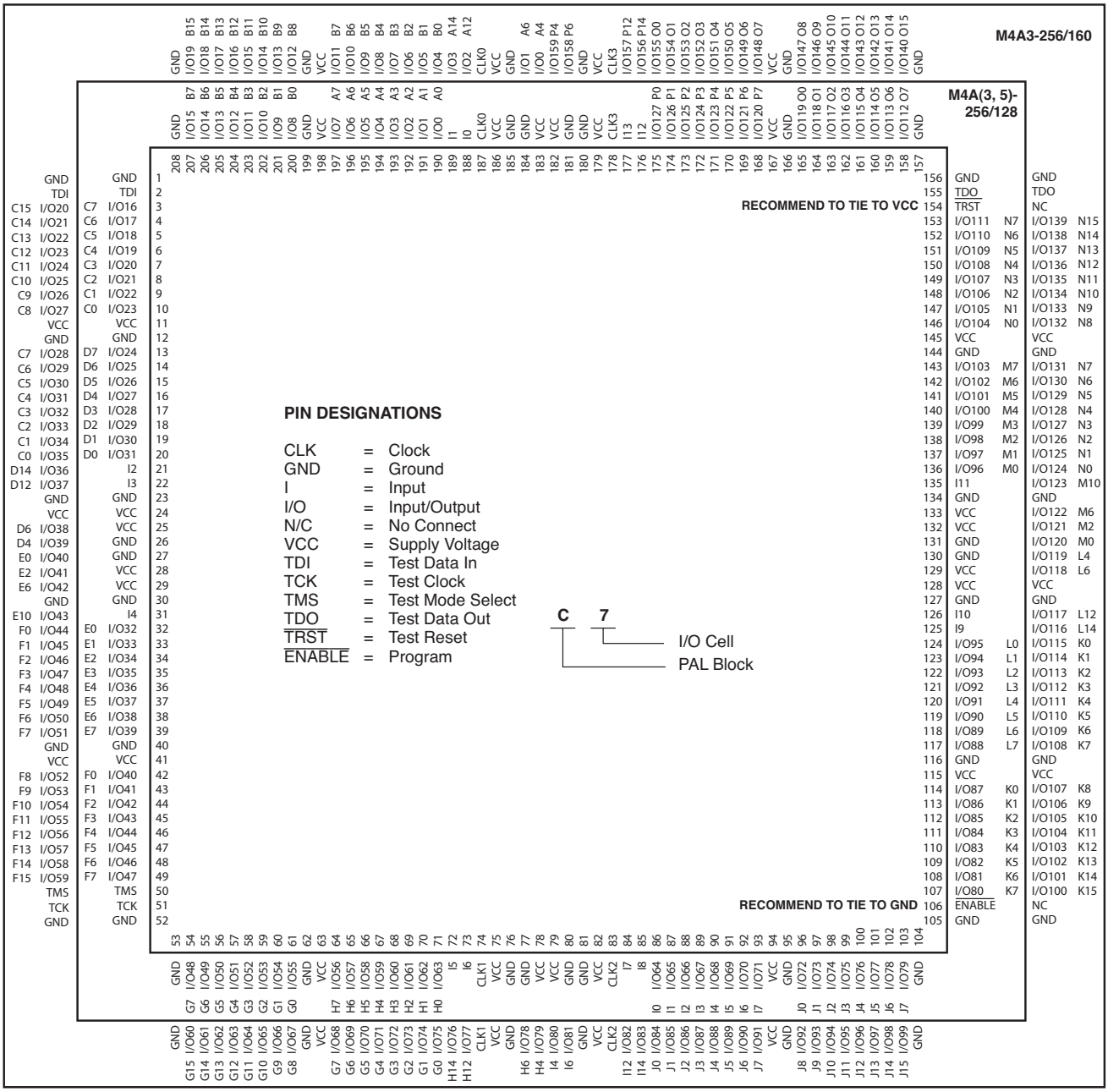
TMS = Test Mode Select

TDO = Test Data Out

208-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-256/128 AND M4A3-256/160)

Top View

208-Pin PQFP



17466G-044

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-256/192)

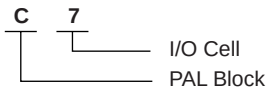
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O167 N15	I/O181 O13	I/O180 O12	I/O177 O9	I/O174 O6	I/O172 O4	I/O191 P14	I/O186 P4	I/O1 A2	I/O3 A6	GCLK0	I/O9 B1	I/O13 B5	I/O15 B7	I/O18 B10	I/O20 B12	A
B	I/O165 N13	I/O166 N14	I/O182 O14	I/O179 O11	I/O175 O7	I/O173 O5	I/O168 O0	I/O187 P6	I/O0 A0	I/O5 A10	I/O7 A14	I/O10 B2	I/O16 B8	I/O19 B11	I/O21 B13	NC	B
C	I/O163 N11	I/O164 N12	NC	I/O183 O15	I/O178 O10	I/O170 O2	I/O171 O3	I/O189 P10	I/O184 P0	I/O6 A12	I/O12 B4	I/O14 B6	I/O23 B15	I/O22 B14	TDI	I/O39 C15	C
D	I/O158 N6	I/O159 N7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O17 B9	I/O38 C14	I/O37 C13	D
E	I/O156 N4	NC	I/O162 N10	VCC	I/O160 N8	I/O161 N9	I/O190 P12	GCLK3	I/O188 P8	I/O2 A4	I/O8 B0	NC	GND	I/O36 C12	I/O35 C11	I/O31 C7	E
F	I/O152 N0	I/O157 N5	I/O155 N3	GND	I/O154 N2	I/O153 N1	I/O176 O8	I/O169 O1	I/O185 P2	I/O4 A8	I/O11 B3	I/O34 C10	VCC	I/O32 C8	I/O30 C6	I/O29 C5	F
G	I/O147 M6	I/O150 M12	I/O149 M10	VCC	I/O148 M8	I/O151 M14	VCC	GND	GND	VCC	I/O33 C9	I/O28 C4	GND	I/O26 C2	I/O25 C1	I/O47 D14	G
H	I/O144 M0	I/O146 M4	I/145 OM2	GND	I/O136 L0	I/O137 L2	GND	VCC	VCC	GND	I/O27 C3	I/O24 C0	VCC	I/O44 D8	I/O43 D6	I/O42 D4	H
J	I/O138 L4	I/O139 L6	I/O140 L8	GND	I/O142 L12	I/O141 L10	GND	VCC	VCC	GND	I/O46 D12	I/O45 D10	GND	I/O49 E2	I/O48 E0	I/O50 E4	J
K	I/O143 L14	I/O120 K0	I/O121 K1	VCC	I/O123 K3	I/O122 K2	VCC	GND	GND	VCC	I/O41 D2	I/O40 D0	VCC	I/O55 E14	I/O54 E12	I/O56 F0	K
L	I/O124 K4	I/O125 K5	I/O127 K7	GND	I/O130 K10	I/O126 K6	I/O98 I4	I/O91 H6	I/O75 G3	I/O77 G5	I/O52 E8	I/O51 E6	GND	I/O59 F3	I/O60 F4	I/O57 F1	L
M	I/O128 K8	I/O129 K9	I/O131 K11	GND	I/O107 J3	I/O105 J1	I/O100 I8	I/O90 H4	I/O74 G2	I/O80 G8	I/O83 G11	I/O53 E10	VCC	I/O68 F12	I/O63 F7	I/O58 F2	M
N	I/O132 K12	I/O133 K13	I/O135 K15	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O64 F8	I/O61 F5	N
P	I/O134 K14	I/O117 J13	I/O118 J14	I/O119 J15	I/O108 J4	I/O106 J2	I/O101 I10	I/O89 H2	I/O93 H10	I/O94 H12	I/O79 G7	I/O84 G12	I/O87 G15	TMS	I/O65 F9	I/O62 F6	P
R	I/O116 J12	I/O115 J11	I/O112 J8	I/O111 J7	I/O104 J0	I/O102 I12	I/O99 I6	I/O96 I0	I/O92 H8	I/O72 G0	I/O76 G4	I/O81 G9	I/O85 G13	I/O71 F15	I/O67 F11	I/O66 F10	R
T	I/O114 J10	I/O113 J9	I/O110 J6	I/O109 J5	I/O103 I14	GCLK2	I/O97 I2	I/O88 H0	GCLK1	I/O95 H14	I/O73 G1	I/O78 G6	I/O82 G10	I/O86 G14	I/O70 F14	I/O69 F13	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



17466G-047

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

M4A3- 256 / 128 -7 Y C

FAMILY TYPE

M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V_{CC})
M4A5- = ispMACH 4A Family Advanced Feature (5-V V_{CC})

MACROCELL DENSITY

32	= 32 Macrocells	192	= 192 Macrocells
64	= 64 Macrocells	256	= 256 Macrocells
96	= 96 Macrocells	384	= 384 Macrocells
128	= 128 Macrocells	512	= 512 Macrocells

I/Os

/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP
/48 = 48 I/Os in 100-pin TQFP
/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA
/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA
/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA
/160 = 160 I/Os in 208-pin PQFP
/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA
/256 = 256 I/Os in 388-ball fpBGA

*Package obsolete, contact factory.

SPEED

-5 = 5.0 ns t_{PD}
-55 = 5.5 ns t_{PD}
-6 = 6.0 ns t_{PD}
-65 = 6.5 ns t_{PD}
-7 = 7.5 ns t_{PD}
-10 = 10 ns t_{PD}
-12 = 12 ns t_{PD}
-14 = 14 ns t_{PD}

PACKAGE TYPE

SA = Ball Grid Array (BGA)
J = Plastic Leaded Chip Carrier (PLCC)
JN = Lead-free Plastic Leaded Chip Carrier (PLCC)
V = Thin Quad Flat Pack (TQFP)
VN = Lead-free Thin Quad Flat Pack (TQFP)
Y = Plastic Quad Flat Pack (PQFP)
YN = Lead-fee Plastic Quad Flat Pack (PQFP)
FA = Fine-pitch Ball Grid Array (fpBGA)
FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)
CA = Chip-array Ball Grid Array (caBGA)

OPERATING CONDITIONS

C = Commercial (0°C to +70°C)
I = Industrial (-40°C to +85°C)

48 = 48-pin TQFP for M4A3-32/32 or M4A3-64/32 M4A5-32/32 or M4A5-64/32

Conventional Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48
M4A3-64/32	-55, -7, -10	JC, VC, VC48
M4A3-64/64		VC
M4A3-96/48		VC
M4A3-128/64		YC, VC, CAC
M4A3-192/96	-6, -7, -10	VC, FAC
M4A3-256/128	-55, -65[1], -7, -10	YC, FAC, SAC
M4A3-256/160	-7, -10	YC
M4A3-256/192		FAC
M4A3-384/160	-65, -10, -12	YC
M4A3-384/192		SAC, FAC
M4A3-512/160	-7, -10, -12	YC
M4A3-512/192		FAC
M4A3-512/256		FAC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	JI, VI, VI48
M4A3-64/32		JI, VI, VI48
M4A3-64/64		VI
M4A3-96/48		VI
M4A3-128/64		YI, VI, CAI
M4A3-192/96		VI, FAI
M4A3-256/128		YI, FAI, SAI
M4A3-256/160	-10, -12	YI
M4A3-256/192		FAI
M4A3-384/160	-10, -12, -14	YI
M4A3-384/192		FAI
M4A3-512/160		YI
M4A3-512/192		FAI
M4A3-512/256		FAI

1. Use 5.5ns for new designs.